

**Product Change Notice**  
**THIS CHANGE AFFECTS HERMETIC OPTOCOUPLEDERS ONLY**

Issue Date: 12 May 2017  
HOC235  
CAGE Code 50434

**Change Type:**

Die wafer process change.

**Parts Affected:**

HCPL-623K	5962-8876905K2A
HCPL-625K	5962-8876906KFC

**Description and Extent of Change:**

Qualification was successfully completed and Avago Technologies will begin to use IC's fabricated utilizing a process change from a solid planar source predeposition doping to a liquid source predeposition doping. This changes the method of depositing phosphorus onto the wafers.

There are no data sheet parameters affected by this change.

**Reasons for Change:**

Reason for change is enhanced process uniformity and stability.

**Effective Date of Change:**

Date of change effective immediately.

GIDEP Product Change Notice, Document JL8-C-17-0003, reflecting this change was published and posted in May 2017.

Shelley A. Sinclair  
Product Line Manager

Ah Chee Neo  
Quality Assurance Manager